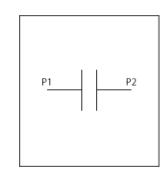


PSpice Model Ceramic Capacitor SAMSUNG CL10B104KB8NNN



Model Information

An original macro model Call Name MDC CL10B104KB8NNN PS

Pin Assian 1:P1 2:P2

File List Model Library MDC_CL10B104KB8NNN_PS01.lib

> Model Report MDC_CL10B104KB8NNN_PS.pdf (this file)

Verified Simulator Version

Note

PSpice version 17.2

References

The information which was used for modeling is as follow:

Company name

[Data Sheet]

Date/Version 2023/08/03

Product name CL10B104KB8NNN

SAMSUNG ELECTRO-MECHANICS, Characteristics CapVf[Freq],CapTemp[Vf],CapTemp[Vf]2,CapVac[Freq],Imp

edanceFreq[Vf],ESRFreq[Vf],CapFreq[Vf]

Simulation Range

This table shows the range of evaluated simulation range that was not occurs any convergence problems in this area.

Item	Range			Unit
	Min.		Max.	
Temperature	-55	to	125	deg C



Model Functions Table

Capacitor

O: Implemented

×: Not Implemented
—: Not applicable

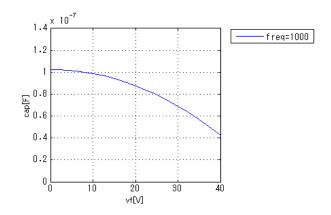
RANK=1

	IVAINIT-1	
Functions	RANK	Implemented
Impedance-Frequency	1	0
ESR-Frequecy	1	0
Capacitance-Frequency	1	0
Inductance-Frequency	1	_
Capacitance-Voltage	1	0
Capacitance-Temp	1	0
Capacitance-Vac	1	0
Resistance-Voltage	1	_



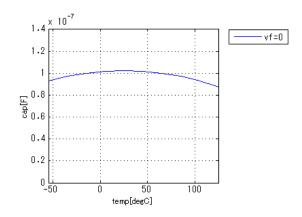
Simulation results are following. Explanatory notes — : simulated

CapVf[Freq]



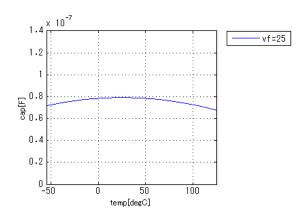
CapTemp[Vf]

Freq = 1000Hz



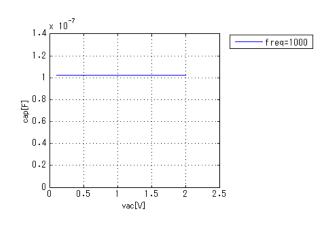
CapTemp[Vf]2

Freq = 1000Hz



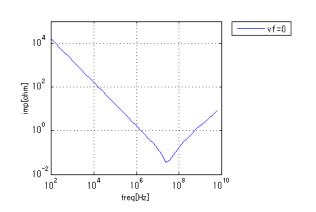
CapVac[Freq]

Vf = 0V



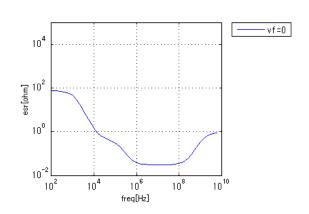
ImpedanceFreq[Vf]

temp = 25degC



ESRFreq[Vf]

temp = 25degC

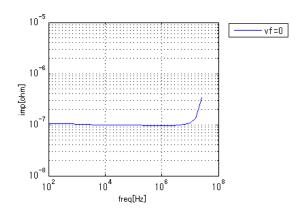




Simulation results are following. Explanatory notes — : simulated

CapFreq[Vf]

Temp = 25degC





DISCLAIMER

- 1. This SPICE (Simulation Program with Integrated Circuit Emphasis) model and its content (the "Contents") are copyright of MoDeCH Inc. All rights reserved. Any redistribution or reproduction of any or all part of the Contents in any form is prohibited without express written permission made by MoDeCH Inc.
- MoDeCH Inc. as licensor (the "Licensor") hereby grants to you, as licensee (the "Licensee"), a nonexclusive, non-transferable license to use the Contents as long as you abide by the terms and conditions of this DISCLAIMER.
- 3. The Licensee is not authorized to sell, loan, rent and redistribute or license the Contents in whole or in part, or in modified form, to anyone.
- 4. The Licensor shall in no way be liable to the Licensee or any third party for any loss or damage (including ,but not limited to, lost profits, or other incidental, consequential, or punitive damages), however caused (including through negligence) which may be directly or indirectly suffered from, arising out of, or in connection with, any use of the Contents.
- 5. Notwithstanding anything contained in this DISCLAIMER, in no event shall Licensor be liable for any claims, damages or loss which may arise from the modification, combination, operation or use of the Contents with the Licensee's computer programs.
- 6. The Licensor does not warrant that the Contents will function in any environment.
- 7. The Contents may be changed or updated without notice. MoDeCH Inc. may also make improvements and/or changes in the products, pricing and/or the programs related to the Contents at any time without notice.



MoDeCH Inc.

Head Office

Location: 5-15 Yokoyama-cho, Hachioji-Shi, Tokyo 192-0081, Japan

Tel:+81-42-656-3360

E-Mail:model-on-support@modech.co.jp

URL:http://www.modech.com/en/

© 2023 MoDeCH Inc. PS-DCC-23-000004-1